

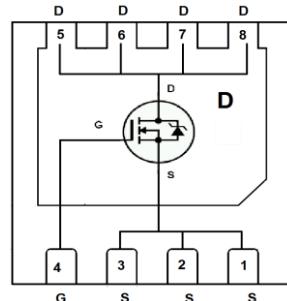
SSC8130GQ4

N-Channel Enhanced MOSFET

➤ Features

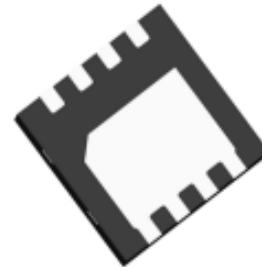
VDS	VGS	RDS(on) Typ.	ID
30V	±20V	6mR@10V	45A
		9mR@4V5	

➤ Pin configuration



➤ Description

This device is N-Channel enhancement MOSFET. Uses advanced trench technology and design to provide excellent RDS(on) with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.



Bottom View

➤ Applications

- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification



➤ Ordering Information

Device	Package	Shipping
SSC8130GQ4	DFN3X3	5000/Reel

Marking

(Y: product year / W: product week)

➤ **Absolute Maximum Ratings($T_A=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
V_{DSS}	Drain-to-Source Voltage	30	V
V_{GSS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current ^d	$T_c=25^\circ\text{C}$	45
		$T_c=100^\circ\text{C}$	28
I_{DSM}	Continuous Drain Current ^a	$T_A=25^\circ\text{C}$	24
		$T_A=70^\circ\text{C}$	16
I_{DM}	Pulsed Drain Current ^b	180	A
P_D	Power Dissipation ^c	$T_c=25^\circ\text{C}$	26
		$T_c=100^\circ\text{C}$	10.5
P_{DSM}	Power Dissipation ^a	$T_A=25^\circ\text{C}$	3.5
		$T_A=70^\circ\text{C}$	2.2
I_{AS}	Avalanche Current ^b L=0.5mH Single Pulse	25	A
E_{AS}	Avalanche Energy ^b L=0.5mH Single Pulse	156	mJ
T_J	Operation junction temperature	-55~150	$^\circ\text{C}$
T_{STG}	Storage temperature range	-55~150	

➤ **Thermal Resistance Ratings($T_A=25^\circ\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	36	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	4.75	

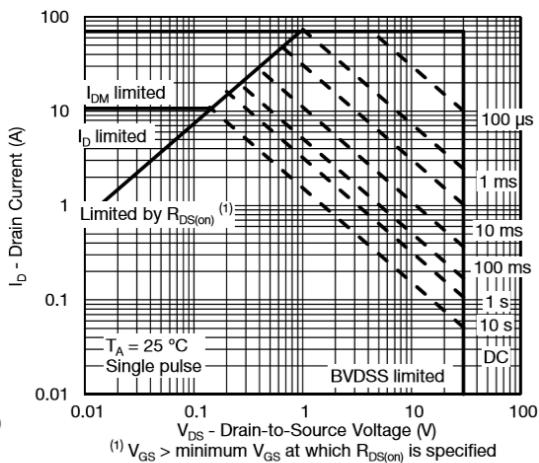
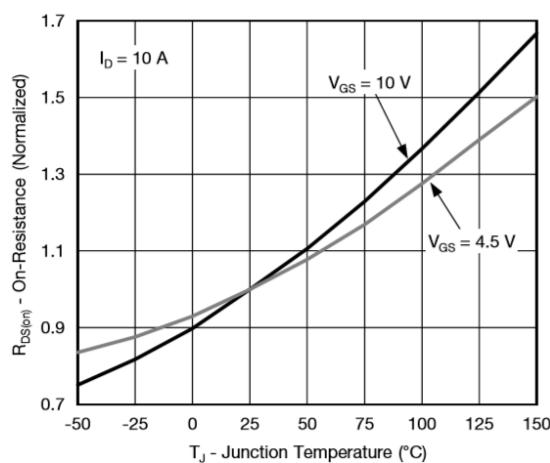
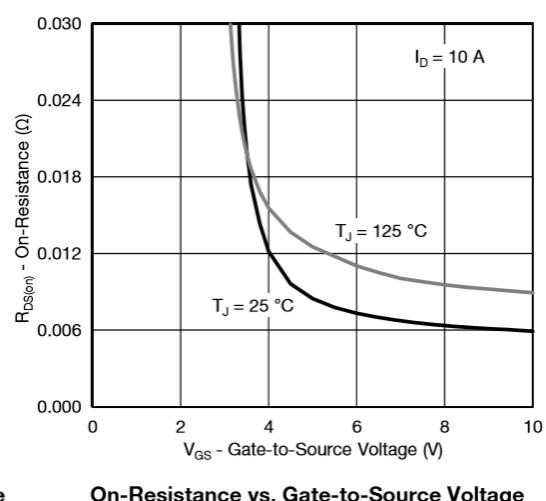
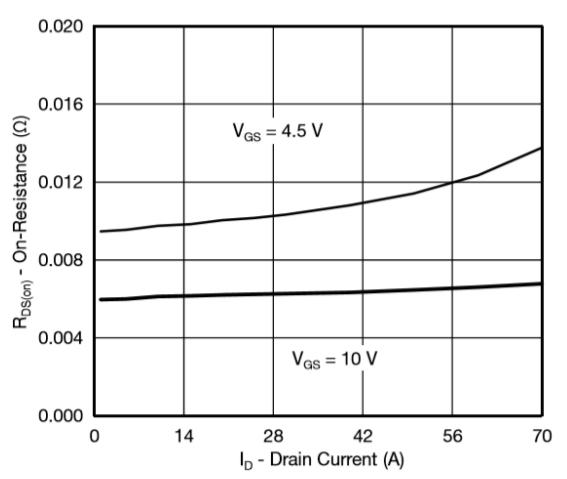
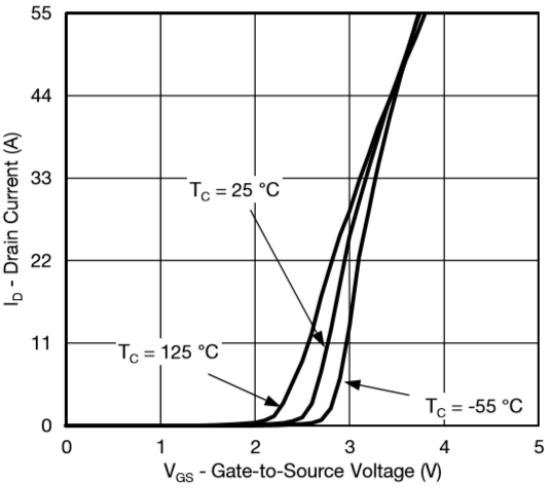
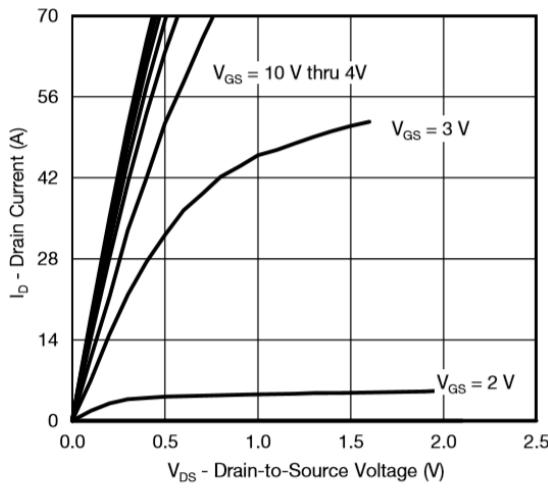
Note:

- a. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

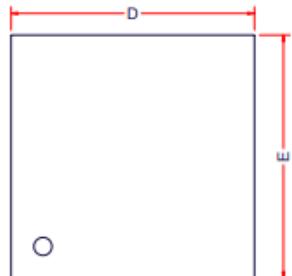
➤ Electronics Characteristics($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$VGS=0V, ID=250\mu A$	30			V
$V_{GS(th)}$	Gate Threshold Voltage	$VDS=VGS, ID=250\mu A$	1	1.7	3	V
$R_{DS(on)}$	Drain-Source On-Resistance	$VGS=10V, ID=20A$		6	8.5	mR
		$VGS=4.5V, ID=10A$		9	12.5	
I_{DSS}	Zero Gate Voltage Drain Current	$VDS=24V, VGS=0V$			1	uA
I_{GSS}	Gate-Source leak current	$VGS=\pm 20V, VDS=0V$			± 100	nA
G_{FS}	Transconductance	$VDS=5V, ID=10A$		17		S
V_{SD}	Forward Voltage	$VGS=0V, IS=5A$		0.78	1.3	V
C_{iss}	Input Capacitance	$VDS=15V, VGS=0V, f=1MHz$		2270		pF
C_{oss}	Output Capacitance			220		
C_{rss}	Reverse Transfer Capacitance			102		
$T_{D(ON)}$	Turn-on delay time	$VGS=10V, RL=3R$		15		ns
Tr	Rise time			7		
$T_{D(OFF)}$	Turn-off delay time			25		
Tf	Fall time			6		
Q_G	Total Gate Charge	$VGS=10V, VDS=15V, ID=20A$		26		nC
Q_{GS}	Gate Source Charge			12		
Q_{GD}	Gate Drain Charge			5.4		
Trr	Diode Recovery Time	$IF=10A, di/dt=100A/\mu s$		40		ns
Qrr	Diode Recovery Charge	$IF=10A, di/dt=100A/\mu s$		55		nC

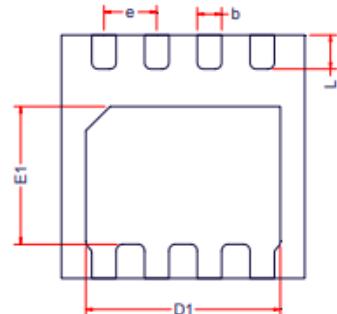
➤ **Typical Characteristics($T_A=25^\circ\text{C}$ unless otherwise noted)**



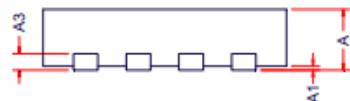
➤ Package Information



TOP VIEW



BOTTOM VIEW

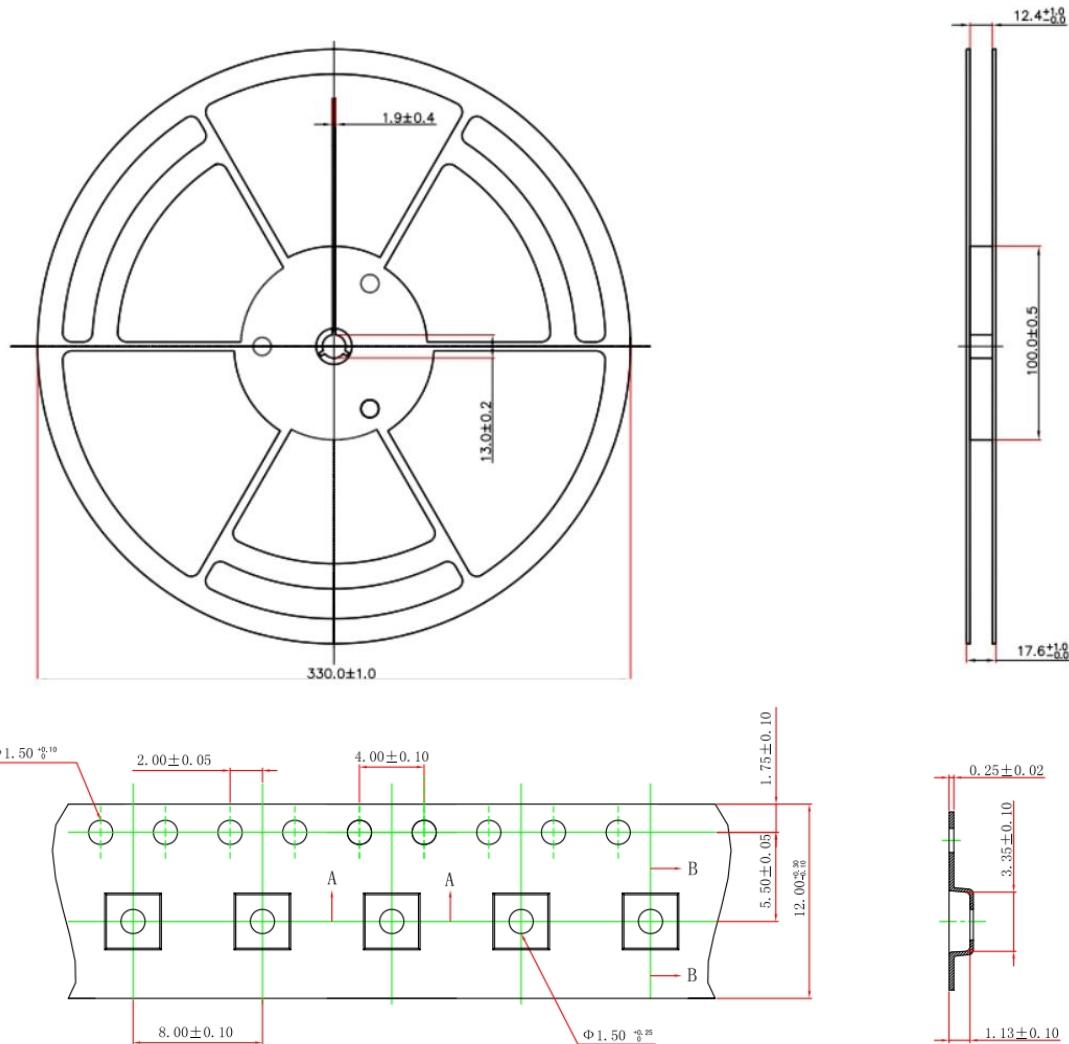


SIDE VIEW

Package: DNF3X3-8L

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	0.20Ref		
D	2.90	3.00	3.10
E	2.90	3.00	3.10
D1	2.35	2.40	2.45
E1	1.65	1.70	1.75
b	0.25	0.30	0.35
e	0.65BSC		
L	0.37	0.42	0.47

➤ Tape and Reel



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